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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	160
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-256-160-10ync

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32	C				C, I	C, I	I	
M4A5-32								
M4A3-64/32		C			C, I	C, I	I	
M4A5-64/32								
M4A3-64/64		C			C, I	C, I	I	
M4A3-96		C			C, I	C, I	I	
M4A5-96								
M4A3-128		C			C, I	C, I	I	
M4A5-128								
M4A3-192			C		C, I	C, I	I	
M4A5-192								
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192					C	C, I	I	
M4A3-256/160								
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

Note:

1. C = Commercial I = Industrial

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in “product term clusters.” The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

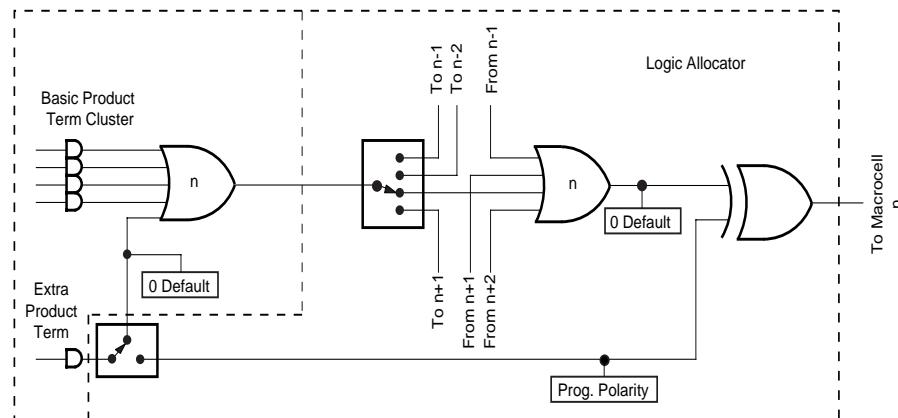
When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.

Table 6. Logic Allocator for All ispMACH 4A Devices (except M4A(3,5)-32/32)

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₇ , C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇ , C ₈	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇ , C ₈ , C ₉	M ₁₅	C ₁₄ , C ₁₅

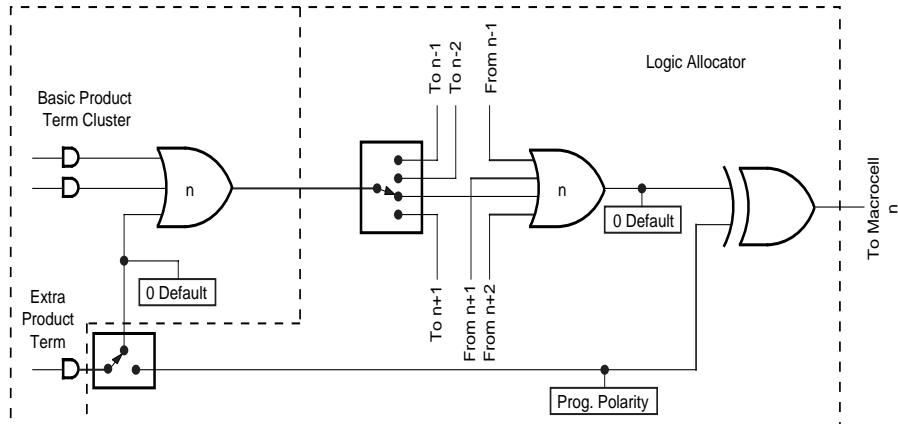
Table 7. Logic Allocator for M4A(3,5)-32/32

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇	M ₁₅	C ₁₄ , C ₁₅



a. Synchronous Mode

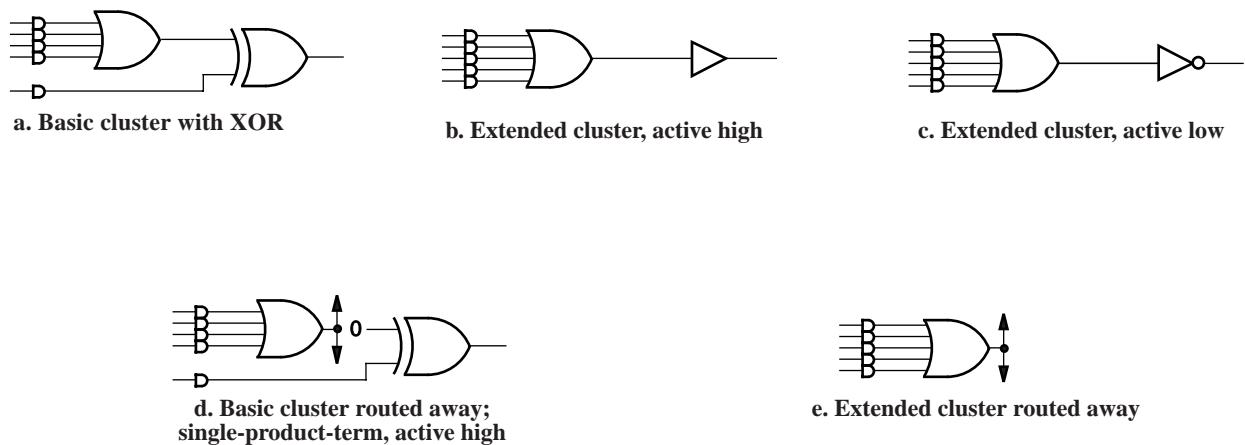
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b. Asynchronous Mode

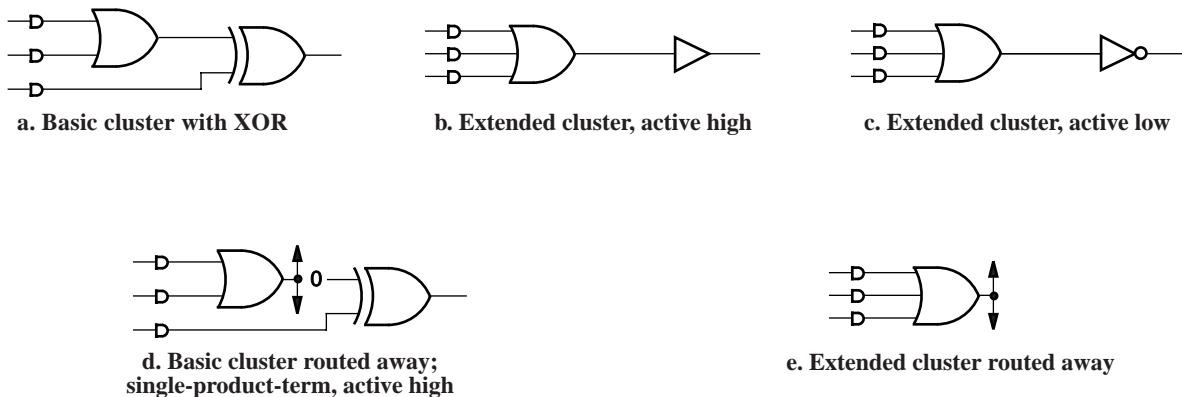
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Figure 2. Logic Allocator: Configuration of Cluster "n" Set by Mode of Macrocell "n"



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Figure 3. Logic Allocator Configurations: Synchronous Mode



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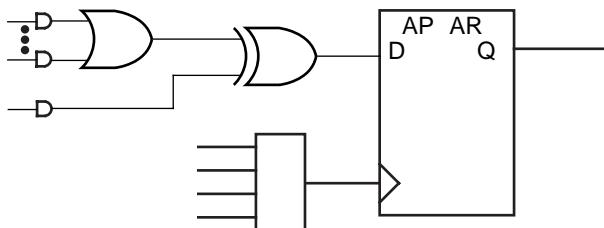
Figure 4. Logic Allocator Configurations: Asynchronous Mode

Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

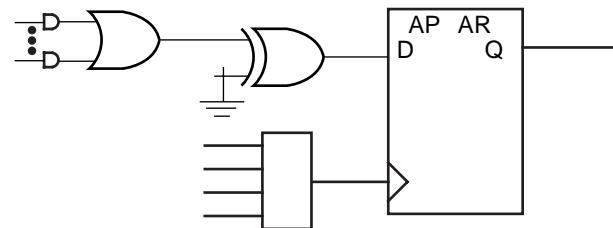
If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-, T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

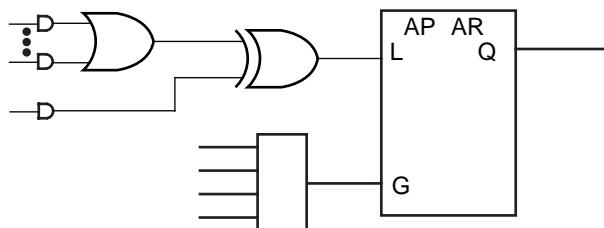
The flip-flop can be configured as a D-type or T-type latch. J-K or S-R registers can be synthesized. The primary flip-flop configurations are shown in Figure 6, although others are possible. Flip-flop functionality is defined in Table 8. Note that a J-K latch is inadvisable as it will cause oscillation if both J and K inputs are HIGH.



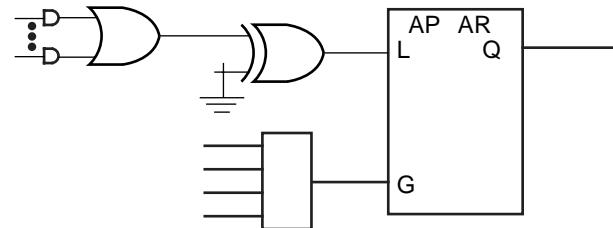
a. D-type with XOR



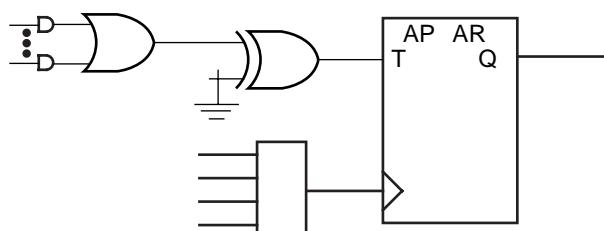
b. D-type with programmable D polarity



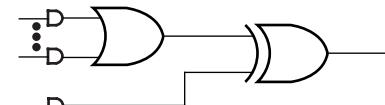
c. Latch with XOR



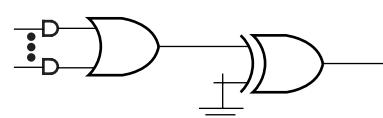
d. Latch with programmable D polarity



e. T-type with programmable T polarity



f. Combinatorial with XOR



g. Combinatorial with programmable polarity

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	Q̄
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

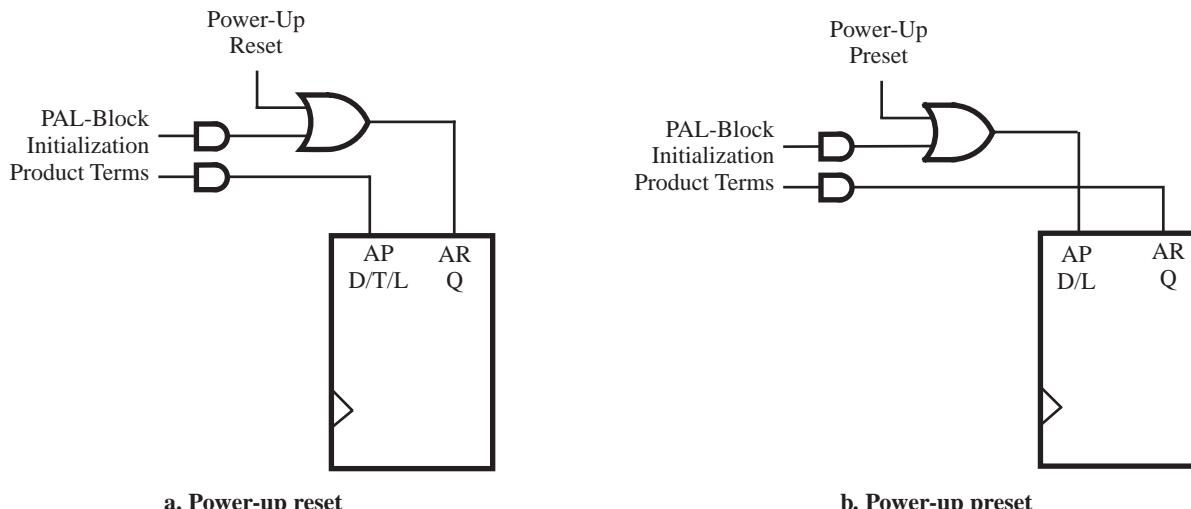
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.

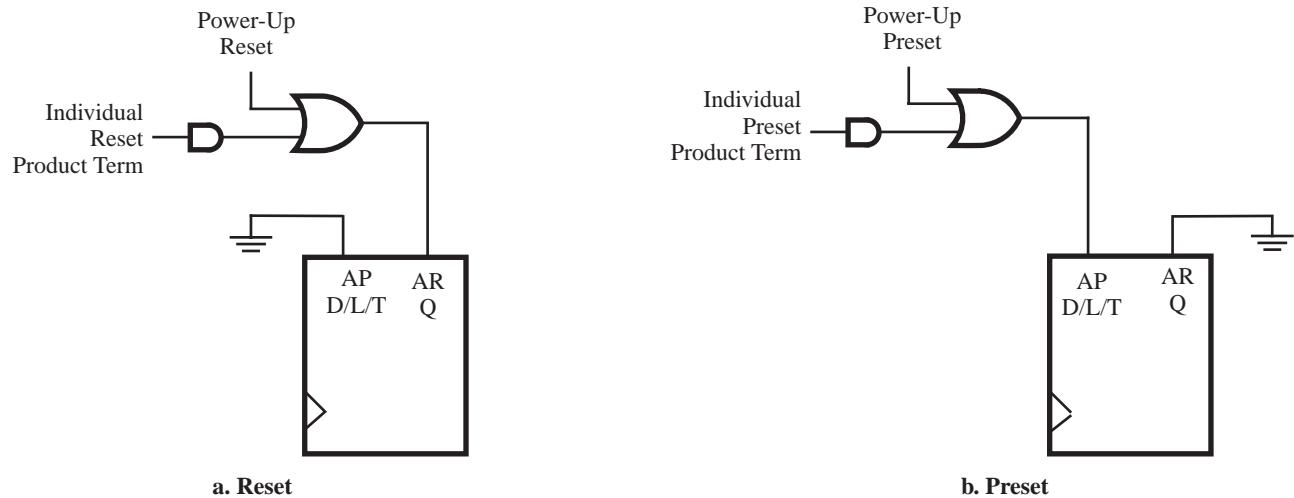


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17466G-013

Figure 7. Synchronous Mode Initialization Configurations

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



17466G-014

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

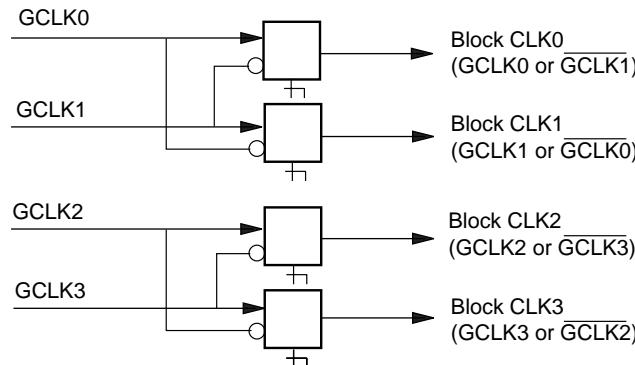
Basic Memory Block Read Operation			
AR	AP	CLK/LE¹	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:-

1. Transparent latch is unaffected by AR , AP

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



17466G-004

Figure 14. PAL Block Clock Generator¹

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations¹

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
<u>GCLK1</u>	GCLK1	X	X
GCLK0	<u>GCLK0</u>	X	X
<u>GCLK1</u>	<u>GCLK0</u>	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	<u>GCLK3 (GCLK1)</u>	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	<u>GCLK2 (GCLK0)</u>
X	X	<u>GCLK3 (GCLK1)</u>	GCLK2 (GCLK0)

Note:

1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

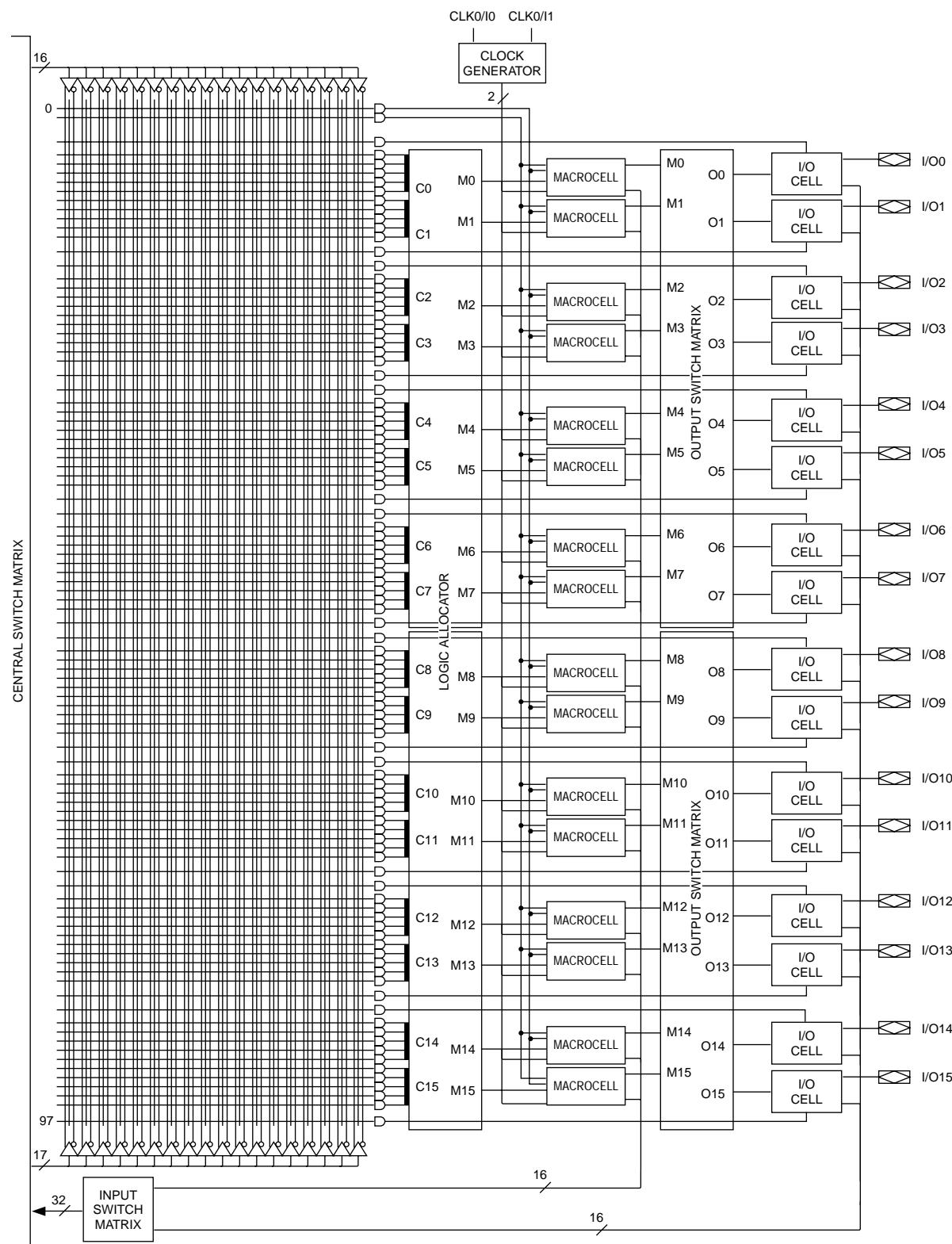
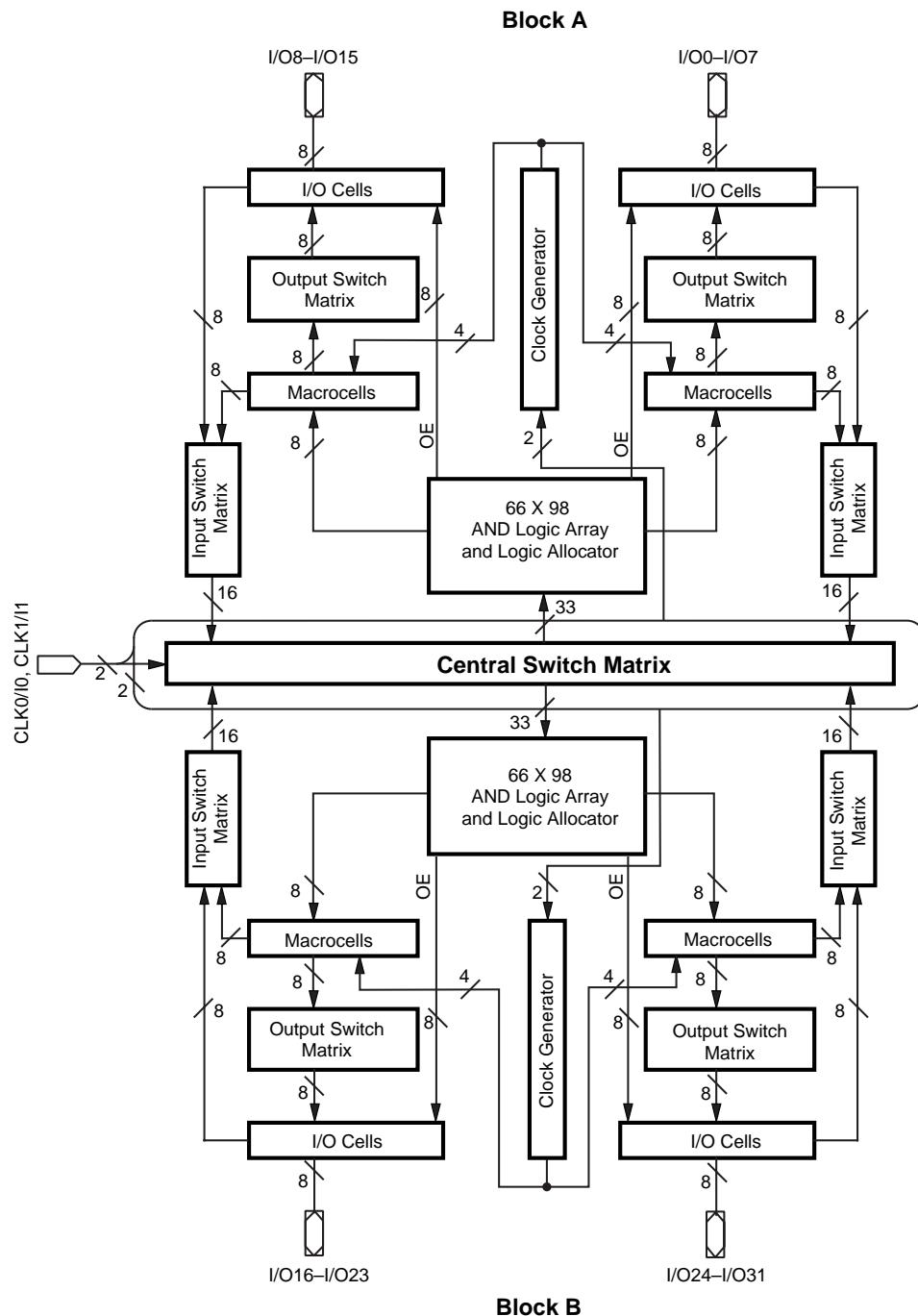


Figure 18. PAL Block for M4A (3,5)-32/32

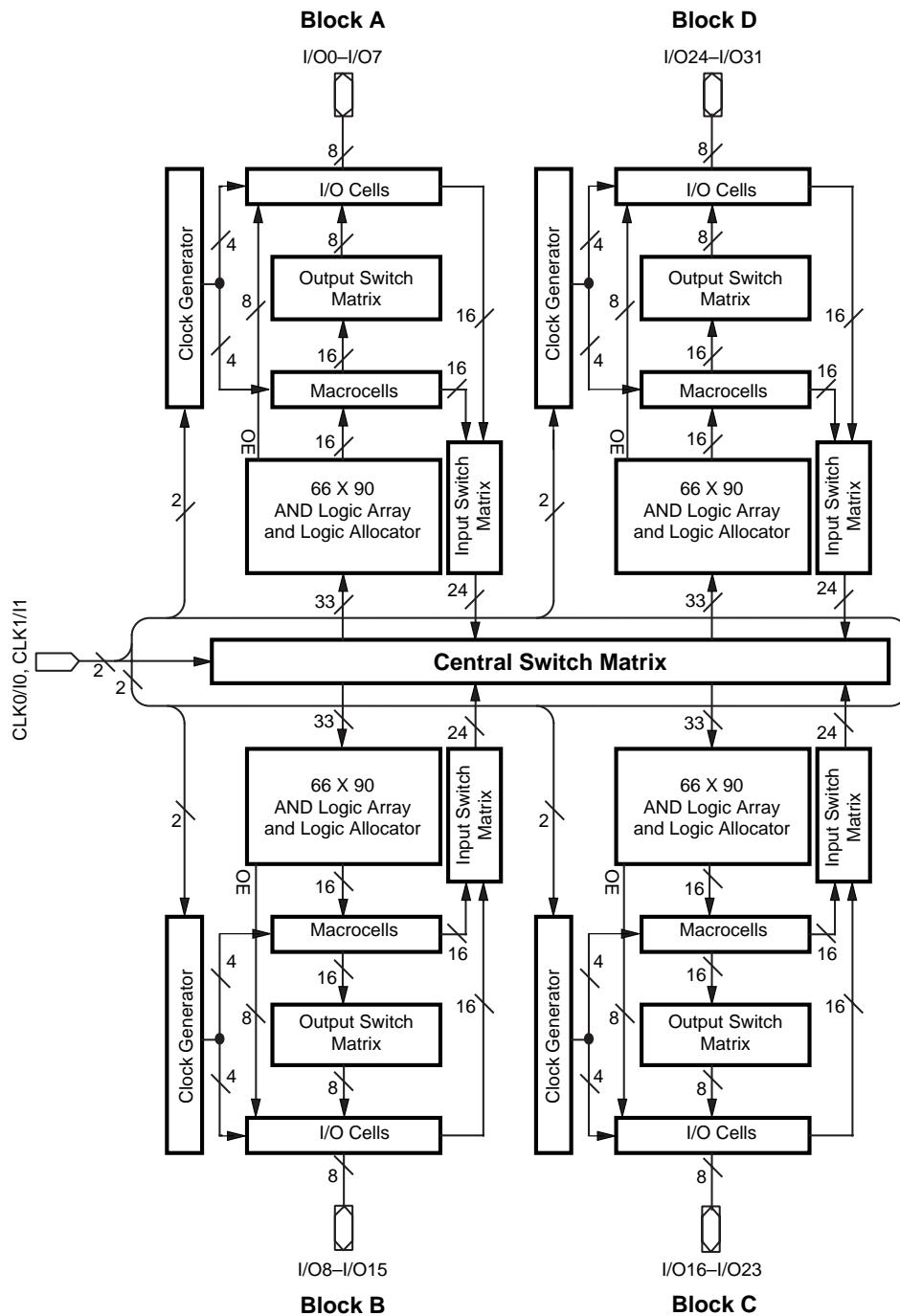
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BLOCK DIAGRAM – M4A(3,5)-32/32

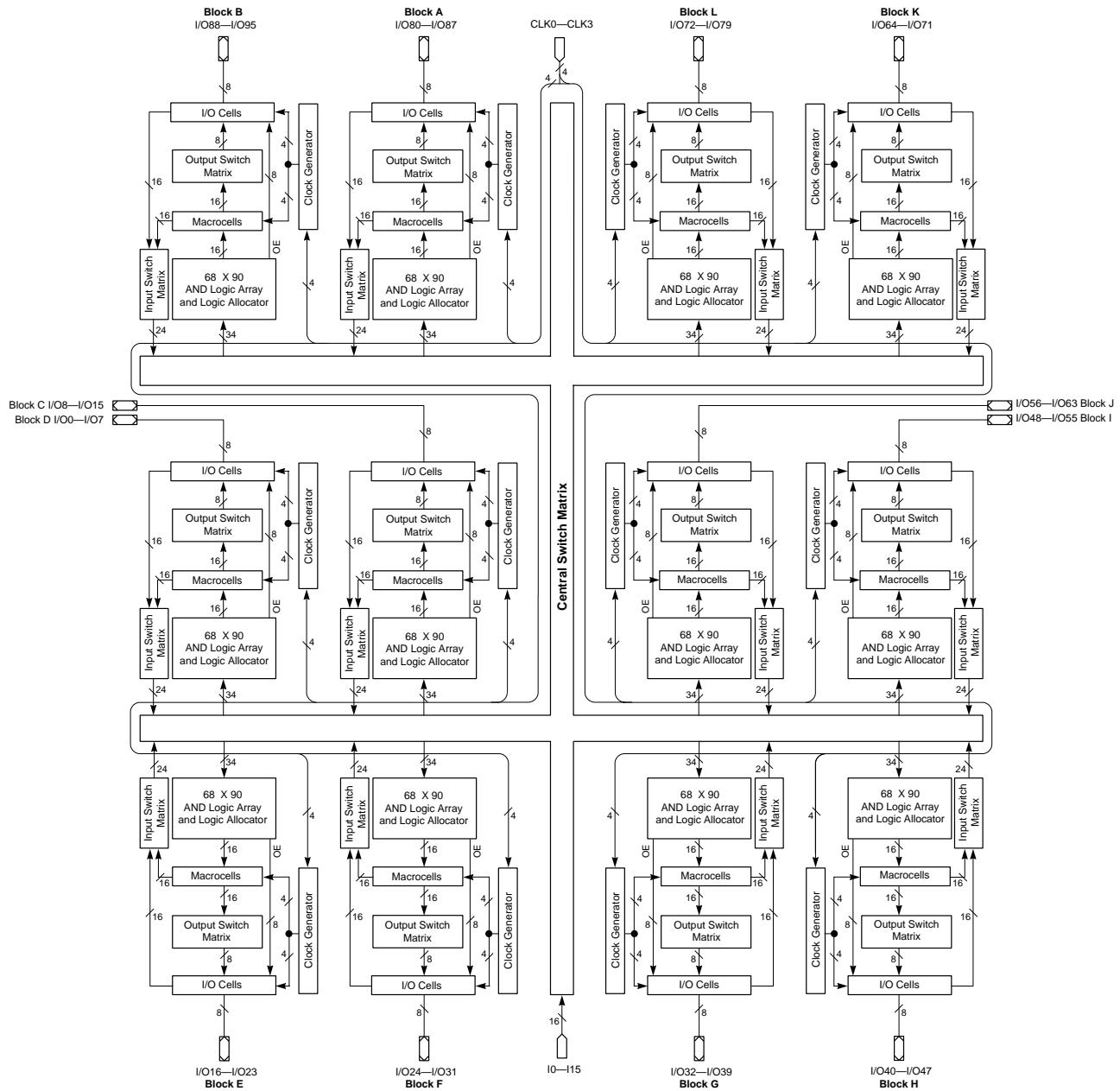


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BLOCK DIAGRAM – M4A(3,5)-64/32



BLOCK DIAGRAM – M4A(3,5)-192/96



17466G-067

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Input Register Delays with ZHT Option:																		
t _{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t _{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{PDIL} Z _i	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t _{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t _{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t _{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t _{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t _{SRI}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t _{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t _{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t _{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WIA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t _{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t _{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power-Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power.

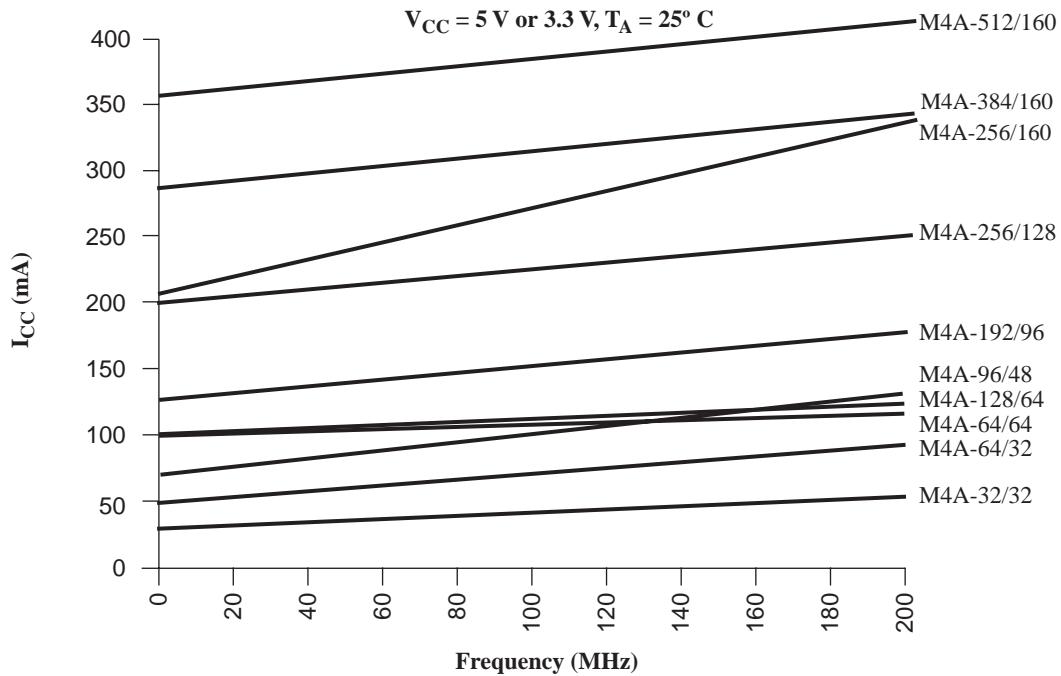


Figure 19. ispMACH 4A I_{CC} Curves at High Speed Mode

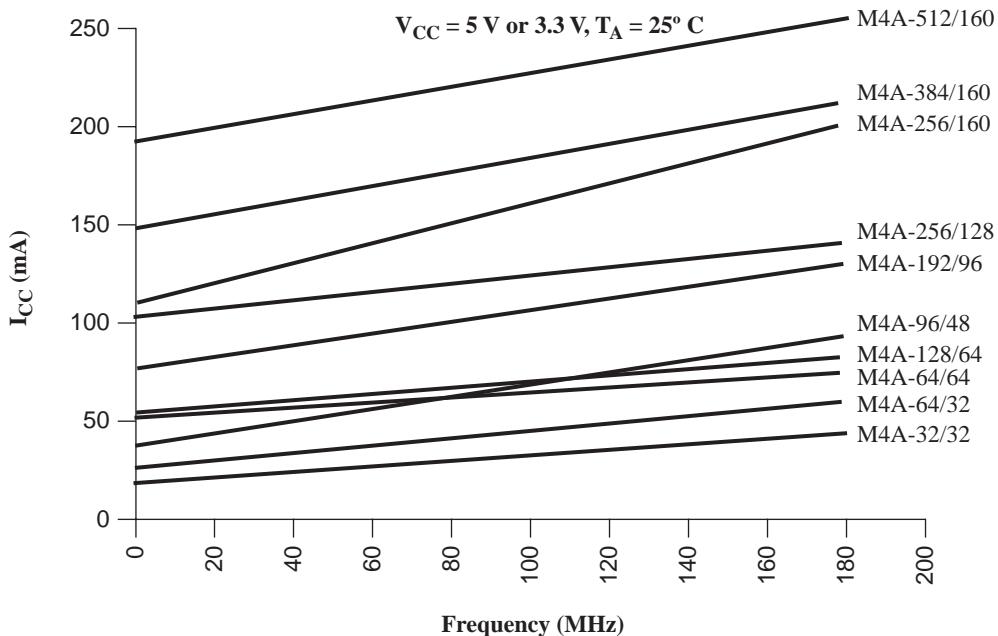
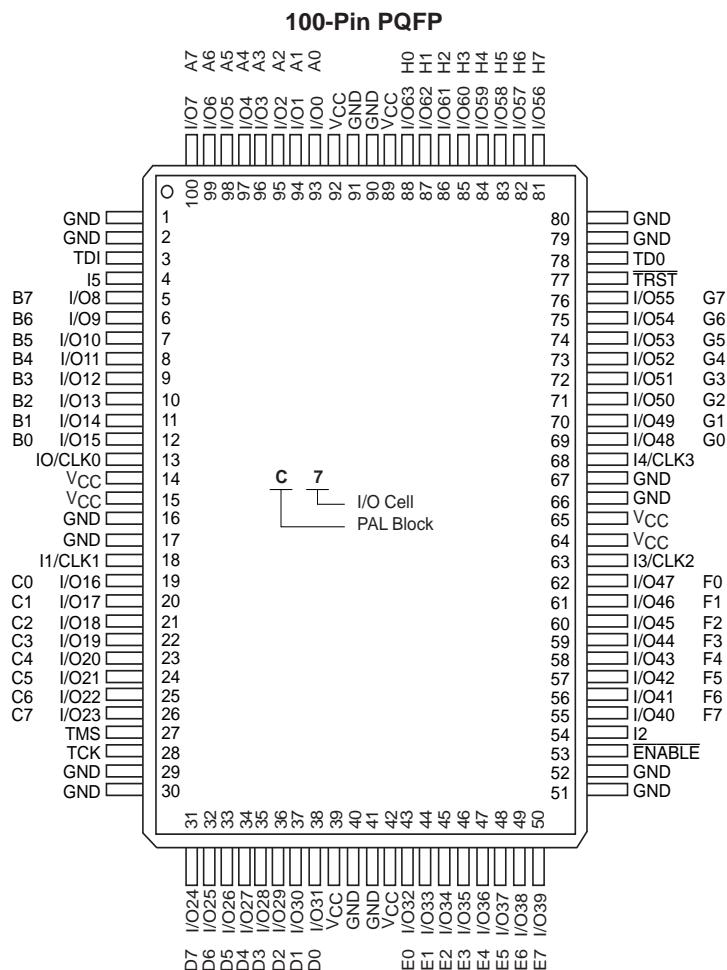


Figure 20. ispMACH 4A I_{CC} Curves at Low Power Mode

100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

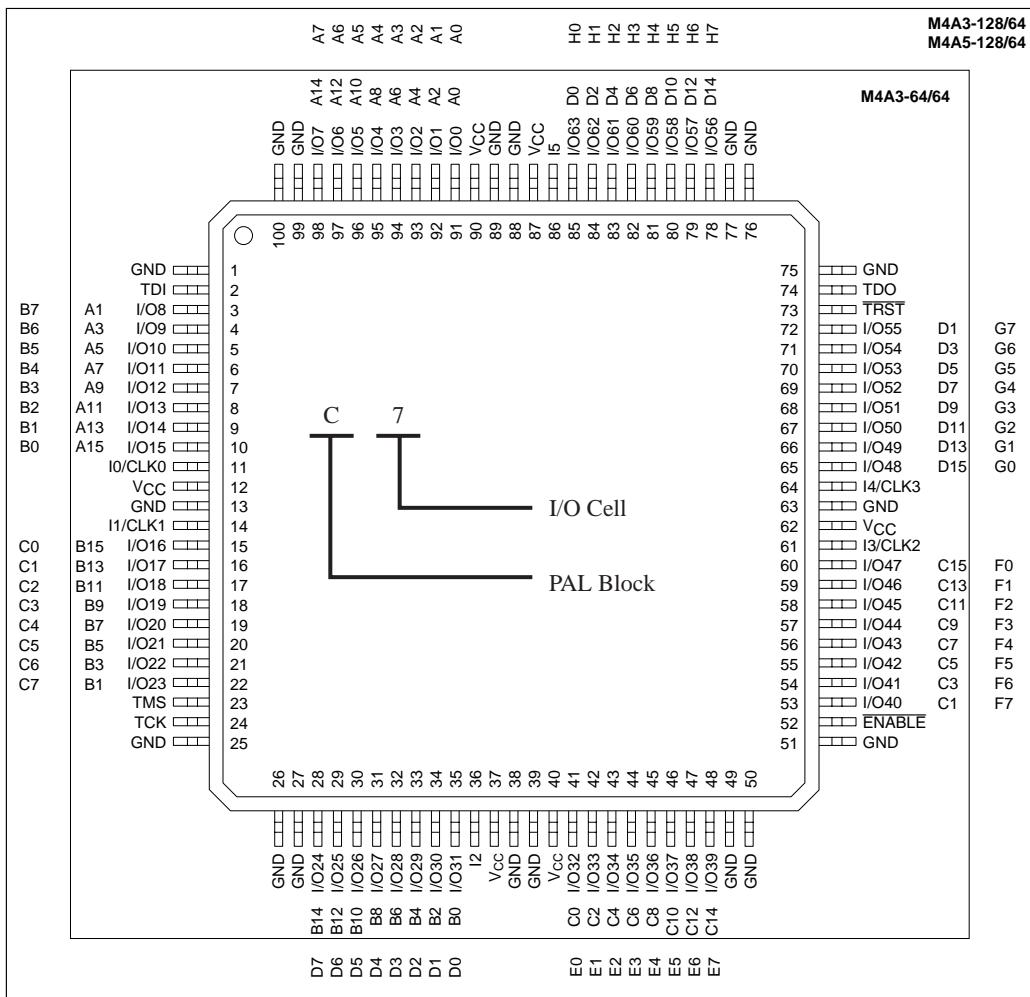
TRST = Test Reset

ENABLE = Program

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View

100-Pin TQFP



17466G-032a

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

Test Reset

ENABLE

ENRIBEE - Program

100-BALL caBGA CONNECTION DIAGRAM (M4A3-128/64)

Bottom View

100-Ball caBGA

	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O63 H7	I/O60 H4	I/O57 H1	GND	GND	I/O1 A1	I/O4 A4	I/O7 A7	GND	A
B	TRST	GND	I/O61 H5	I5	VCC	I/O0 A0	I/O6 A6	GND	TDI	I/O15 B7	B
C	I/O53 G5	TDO	I/O62 H6	I/O58 H2	I/O56 H0	I/O2 A2	GND	I/O14 B6	I/O13 B5	I/O12 B4	C
D	I/O50 G2	I/O55 G7	GND	I/O59 H3	I/O3 A3	I/O5 A5	I/O11 B3	I/O10 B2	CLK0/I0	I/O9 B1	D
E	CLK3/I4	I/O49 G1	I/O51 G3	I/O54 G6	VCC	I/O16 C0	I/O20 C4	I/O8 B0	VCC	GND	E
F	GND	VCC	I/O40 F0	I/O52 G4	I/O48 G0	VCC	I/O22 C6	I/O19 C3	I/O17 C1	CLK1/I1	F
G	I/O41 F1	CLK2/I3	I/O42 F2	I/O43 F3	I/O37 E5	I/O35 E3	I/O27 D3	GND	I/O23 C7	I/O18 C2	G
H	I/O44 F4	I/O45 F5	I/O46 F6	GND	I/O34 E2	I/O24 D0	I/O26 D2	I/O30 D6	TCK	I/O21 C5	H
J	I/O47 F7	ENABLE	GND	I/O38 E6	I/O32 E0	VCC	I2	I/O29 D5	GND	TMS	J
K	GND	I/O39 E7	I/O36 E4	I/O33 E1	GND	GND	I/O25 D1	I/O28 D4	I/O31 D7	GND	K

10 9 8 7 6 5 4 3 2 1

PIN DESIGNATIONS

CLK	= Clock
GND	= Ground
I	= Input
I/O	= Input/Output
N/C	= No Connect
VCC	= Supply Voltage
TDI	= Test Data In
TCK	= Test Clock
TMS	= Test Mode Select
TDO	= Test Data Out
TRST	= Test Reset
ENABLE	= Program

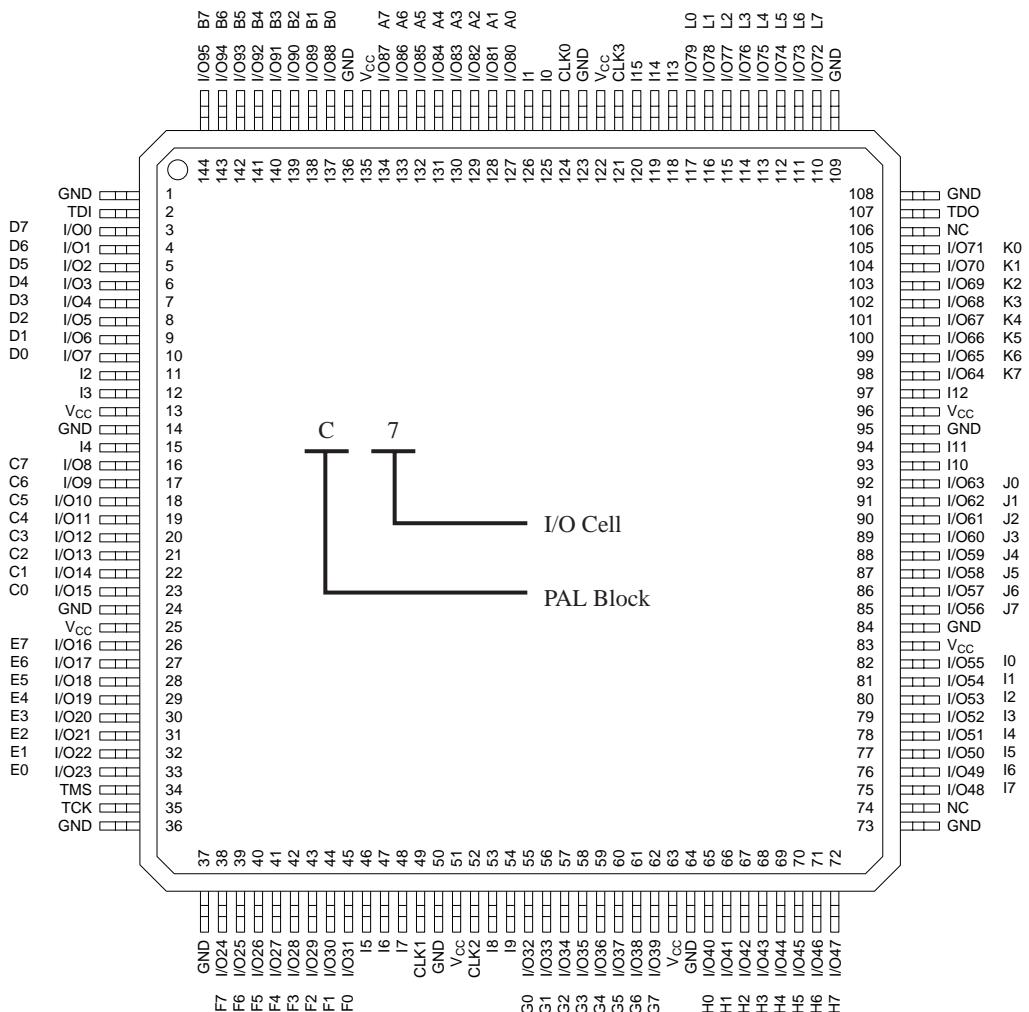


17466G-100cabga

144-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-192/96)

Top View

144-Pin TQFP



17466G-033

PIN DESIGNATIONS

CLK = Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Volta

TDI = Test Data Im

TCK = Test Clock

TMS = Test Mode

TDO = Test Data Out

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/192)

Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O159 KX7	I/O181 OX5	I/O180 OX4	I/O177 OX1	I/O174 NX6	I/O172 NX4	I/O191 PX7	I/O186 PX2	I/O1 A1	I/O3 A3	CLK0	I/O17 C1	I/O21 C5	I/O23 C7	I/O10 B2	I/O12 B4	A
B	I/O157 KX5	I/O158 KX6	I/O182 OX6	I/O179 OX3	I/O175 NX7	I/O173 NX5	I/O168 NX0	I/O187 PX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O18 C2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O155 KX3	I/O156 KX4	N/C	I/O183 OX7	I/O178 OX2	I/O170 NX2	I/O171 NX3	I/O189 PX5	I/O184 PX0	I/O6 A6	I/O20 C4	I/O22 C6	I/O15 B7	I/O14 B6	TDI	I/O39 F7	C
D	I/O150 JX6	I/O151 JX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O38 F6	I/O37 F5	D
E	I/O148 JX4	N/C	I/O154 KX2	VCC	I/O152 KX0	I/O153 KX1	I/O190 PX6	CLK3	I/O188 PX4	I/O2 A2	I/O16 C0	N/C	GND	I/O36 F4	I/O35 F3	I/O47 G7	E
F	I/O144 JX0	I/O149 JX5	I/O147 JX3	GND	I/O146 JX2	I/O145 JX1	I/O176 OX0	I/O169 NX1	I/O185 PX1	I/O4 A4	I/O19 C3	I/O34 F2	VCC	I/O32 F0	I/O46 G6	I/O45 G5	F
G	I/O163 LX3	I/O166 LX6	I/O165 LX5	VCC	I/O164 LX4	I/O167 LX7	VCC	GND	GND	VCC	I/O33 F1	I/O44 G4	GND	I/O42 G2	I/O41 G1	I/O31 E7	G
H	I/O160 LX0	I/O162 LX2	I/O161 LX1	GND	I/O120 EX0	I/O121 EX1	GND	VCC	VCC	GND	I/O43 G3	I/O40 G0	VCC	I/O28 E4	I/O27 E3	I/O26 E2	H
J	I/O122 EX2	I/O123 EX3	I/O124 EX4	GND	I/O126 EX6	I/O125 EX5	GND	VCC	VCC	GND	I/O30 E6	I/O29 E5	GND	I/O65 L1	I/O64 L0	I/O66 L2	J
K	I/O127 EX7	I/O136 GX0	I/O137 GX1	VCC	I/O139 GX3	I/O138 GX2	VCC	GND	GND	VCC	I/O25 E1	I/O24 E0	VCC	I/O71 L7	I/O70 L6	I/O48 J0	K
L	I/O140 GX4	I/O141 GX5	I/O143 GX7	GND	I/O130 FX2	I/O142 GX6	I/O98 AX2	I/O91 P3	I/O75 N3	I/O77 N5	I/O68 L4	I/O67 L3	GND	I/O51 J3	I/O52 J4	I/O49 J1	L
M	I/O128 FX0	I/O129 FX1	I/O131 FX3	GND	I/O115 CX3	I/O113 CX1	I/O100 AX4	I/O90 P2	I/O74 N2	I/O80 O0	I/O83 O3	I/O69 L5	VCC	I/O60 K4	I/O55 J7	I/O50 J2	M
N	I/O132 FX4	I/O133 FX5	I/O135 FX7	VCC	GND	VCC	GND	VCC	GND	VCC	GND	GND	TCK	I/O56 K0	I/O53 J5	N	
P	I/O134 FX6	I/O109 BX5	I/O110 BX6	I/O111 BX7	I/O116 CX4	I/O114 CX2	I/O101 AX5	I/O89 P1	I/O93 P5	I/O94 P6	I/O79 N7	I/O84 O4	I/O87 O7	TMS	I/O57 K1	I/O54 J6	P
R	I/O108 BX4	I/O107 BX3	I/O104 BX0	I/O119 CX7	I/O112 CX0	I/O102 AX6	I/O99 AX3	I/O96 AX0	I/O92 P4	I/O72 N0	I/O76 N4	I/O81 O1	I/O85 O5	I/O63 K7	I/O59 K3	I/O58 K2	R
T	I/O106 BX2	I/O105 BX1	I/O118 CX6	I/O117 CX5	I/O103 AX7	CLK2	I/O97 AX1	I/O88 P0	CLK1	I/O95 P7	I/O73 N1	I/O78 N6	I/O82 O2	I/O86 O6	I/O62 K6	I/O61 K5	T

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out

